

Electronic Patent Application Fee Transmittal

Application Number:	10731453			
Filing Date:	09-Dec-2003			
Title of Invention:	Wafer-level chip scale package and method for fabricating and using the same			
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Filer:	kenneth E. Horton/Jenni Harries			
Attorney Docket Number:	11948.25			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810